



## New Bosch wafer fab in Dresden, Germany

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### General information

- ▶ Total investment approx. 1 billion euros
- ▶ Start of construction work planned for end 2017 / beginning of 2018
- ▶ Completion by end 2019, production scheduled to begin end 2021
- ▶ Plot approx. 60,000 m<sup>2</sup>
- ▶ Building one building with up to 15,000 m<sup>2</sup> shopfloor space and separate office space
- ▶ Associates on site up to 700 (planned)

### Information on wafer manufacturing at Bosch

- ▶ Current portfolio acceleration, yaw-rate, mass-flow, pressure, and environmental sensors, as well as microphones, power semiconductors, and application-specific integrated circuits (ASICs) for vehicle ECUs.
- ▶ Manufacturing sites Reutlingen, Germany (6-inch and 8-inch technology)

- ▶ Production volume  
From Reutlingen, Bosch delivers some 4 million MEMS and roughly 1.5 million ASICs every day
- ▶ Patents  
Bosch holds more than 1,000 patents and patent applications related to MEMS technology
- ▶ Award  
2008 German innovation and advanced technology prize for pioneering work in surface micromachining
- ▶ History  
For more than 45 years, Bosch has been developing and manufacturing microelectronic components and systems. 20 years ago, Bosch developed the microfabrication technique for microelectromechanical systems (MEMS). Today, it is the world market leader.

## Bosch in Germany

- ▶ Headquarters  
Gerlingen-Schillerhöhe, near Stuttgart, Germany
- ▶ Sales revenue  
2016: 14.5 billion euros (worldwide 73.1 billion euros)
- ▶ Headcount  
some 134,000 associates, of which some 26,800 researchers and engineers; worldwide, some 390,000 associates (December 31, 2016)
- ▶ Locations  
70, of which 39 R&D locations (December 31, 2016)